APS search

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 => s 438/485/cclst and 438/487/cclst
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 => s 438/487/cclst and laser# and (TFT or thin film transistor#)
             121 438/487/CCLST
         132285 LASER#
            4276 TFT
         435549 THIN
         348855 FILM
         166425 TRANSISTOR#
           5433 THIN FILM TRANSISTOR#
                   (THIN(W)FILM(W)TRANSISTOR#)
L2
              68 438/487/CCLST AND LASER# AND (TFT OR THIN FILM TRANSISTOR#)
=> s 12 and (SiO or silicon(w)(oxide# or dioxide#))
          76221 SIO
         201578 SILICON
         351523 OXIDE#
         165688 DIOXIDE#
          53745 SILICON(W) (OXIDE# OR DIOXIDE#)
L3
             58 L2 AND (SIO OR SILICON(W) (OXIDE# OR DIOXIDE#))
=> s 13 and (plasma# or PECVD or glow discharq?)
          82627 PLASMA#
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2232 PECVD 16099 GLOW (GLOW (W) DISCHARG?)

L4 51 L3 AND (PLASMA# OR PECVD OR GLOW DISCHARG?)

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